

# Power Electronics



FACHHOCHSCHULE KIEL  
University of Applied Sciences



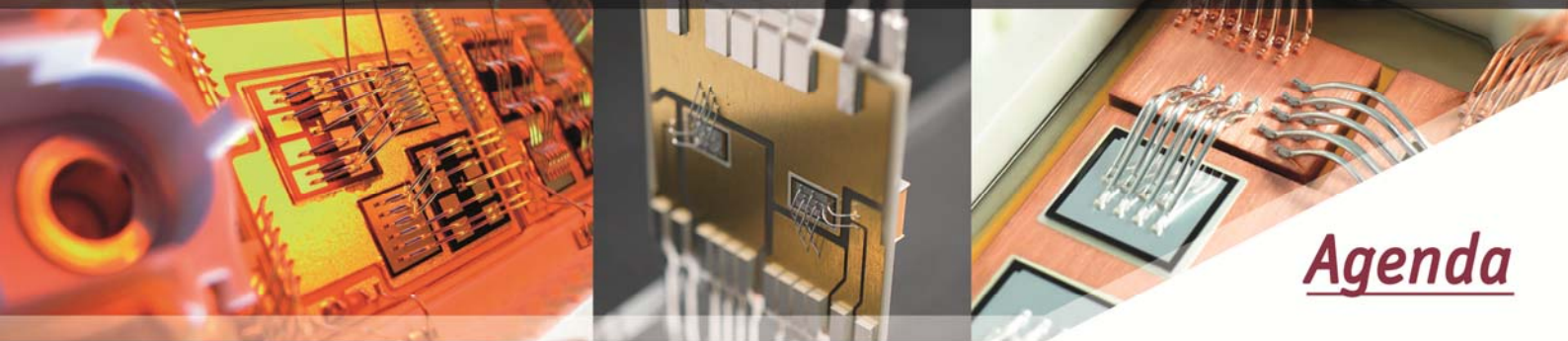
Escuela de  
Ingeniería y Arquitectura  
Universidad Zaragoza

*Thermal management in power electronics packaging*

*Power electronics is the key of conversion of electrical energy*



*Power electronics ensures efficient energy production and consumption*



## Agenda

- *Part 1: Introduction to Kiel packaging lab of University of Applied Sciences in Kiel*
- *Part 2: State of the art of power electronics packaging*
  - *Improved substrate for power modules // Aylin Bicakci (PhD student)*
  - *Hybrid metal - New heat spreader for power electronic devices // Stefan Söhl (PhD student)*
  - *Improved encapsulation for heat dissipating semiconductors // Stefan Behrendt (PhD student)*
  - *SiC-Semiconductors - A demanding packaging task // Daniel Splett (project engineer)*
  - *Cooling of power modules // Dominik Hilper (project engineer)*

*If we have caught your attention, you are kindly invited to participate...*

**14. February 2017, 9:30 – 13:30**  
**Edificio CIRCE, Campus Río Ebro**



Instituto Universitario de Investigación Mixto  
**circe**  
Universidad Zaragoza

*Power electronics is now reaching the limit of technical and thermal capabilities. The University of Applied Sciences in Kiel research successfully on new power modules assembly and joining technologies to realize the ever-increasing demands of the power electronics.*

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